

Claims

1. A method for temporary bonding of a product substrate (2) to a carrier substrate (6) with the following method steps:

- application of an interconnect layer (5) to a product substrate receiving side (6o) of the carrier substrate (6) in an interconnect surface section (13) of the product substrate receiving side (6o),
- application of an antiadhesion layer (4) with low adhesion force to one interconnect side (2u) of the product substrate (2) in an antiadhesion surface section (15) of the interconnect side (2u), which section corresponds to the interconnect surface section (13) at least partially, preferably essentially completely, in terms of area, wherein a receiving space (14) being formed which is bordered by the interconnect layer (5) and the carrier substrate (6) as well as the product substrate (2) and the antiadhesion layer (4) for accommodating structures (3) which are provided on the interconnect side (2u) of the product substrate (2) and which project from the interconnect side (2u),
- alignment of the product substrate (2) relative to the carrier substrate (6) and bonding of the interconnect layer (5) to the antiadhesion layer (4) on one contact surface (16).

2. The method as claimed in Claim 1, wherein ~~an~~ the interconnect surface section (13) is located on the lateral periphery (6s) of the carrier substrate (6), especially in a ring section which is preferably concentric to the product substrate receiver (6o).